



PMEG4015EPK-Q

40 V, 1.5 A low VF Schottky barrier rectifier

20 September 2023

Product data sheet

1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a leadless ultra small SOD1608 (DFN1608D-2) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

2. Features and benefits

- Average forward current: $I_{F(AV)} \leq 1.5$ A
- Reverse voltage: $V_R \leq 40$ V
- Low forward voltage $V_F \leq 610$ mV
- Low reverse current
- Solderable side pads
- Package height typ. 0.37 mm
- Ultra small and leadless SMD plastic package
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- LED backlight for mobile application
- Low power consumption applications
- Ultra high-speed switching
- Reverse polarity protection

4. Quick reference data

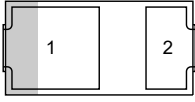

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20$ kHz; square wave; $T_{amb} \leq 65$ °C	-	-	1.5	A
		$\delta = 0.5$; $f = 20$ kHz; square wave; $T_{sp} \leq 135$ °C	-	-	1.5	A
V_R	reverse voltage	$T_j = 25$ °C	-	-	40	V
V_F	forward voltage	$I_F = 1.5$ A; pulsed; $t_p \leq 300$ μ s; $\delta \leq 0.02$; $T_j = 25$ °C	-	540	610	mV
I_R	reverse current	$V_R = 10$ V; $T_j = 25$ °C	-	1	5	μ A
t_{rr}	reverse recovery time	$I_F = 0.5$ A; $I_R = 0.5$ A; $I_{R(meas)} = 0.1$ A; $T_j = 25$ °C	-	4	-	ns

[1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al₂O₃, standard footprint.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode ^[1]	 <p>Transparent top view DFN1608D-2 (SOD1608)</p>	 <p>sym001</p>
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

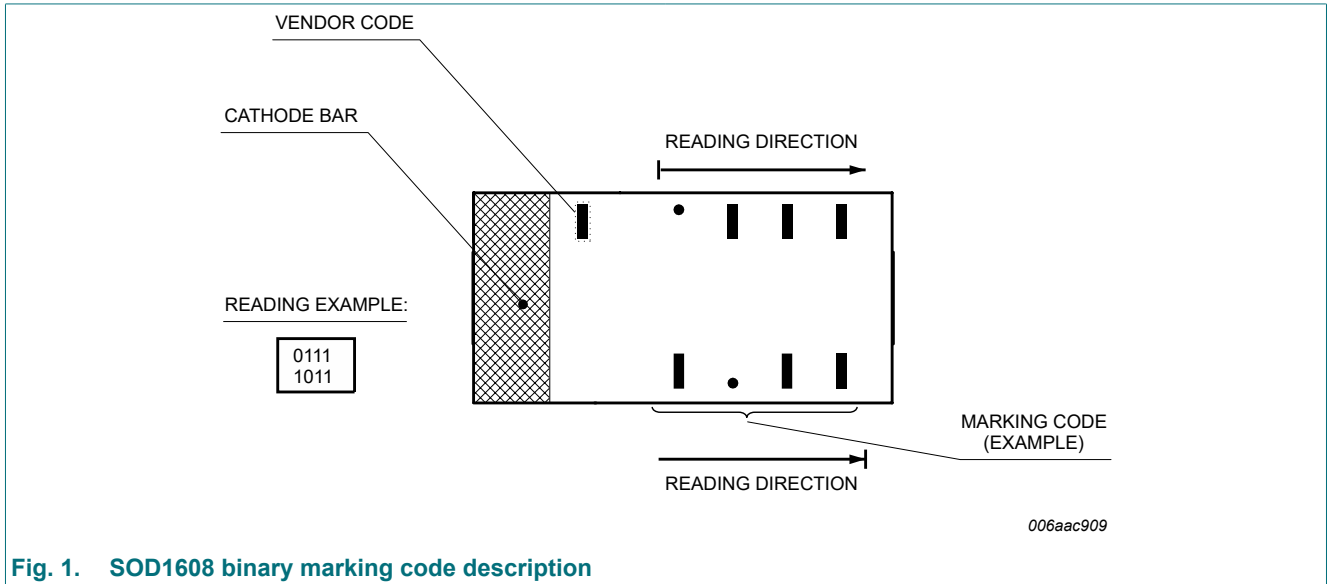
Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG4015EPK-Q	DFN1608D-2	plastic, leadless ultra small plastic package with side-wettable flanks (SWF); 2 terminals; 0.94 mm pitch; 1.6 mm x 0.8 mm x 0.37 mm body	SOD1608

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG4015EPK-Q	0110 0000



8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ °C}$		-	40	V
I_F	forward current	$T_{sp} \leq 130\text{ °C}$		-	2.1	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{amb} \leq 65\text{ °C}$	[1]	-	1.5	A
		$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{sp} \leq 135\text{ °C}$		-	1.5	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1\text{ ms}$; $\delta \leq 0.25$		-	4	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8\text{ ms}$; square wave; $T_{j(\text{init})} = 25\text{ °C}$		-	5	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[2] [3]	-	415	mW
			[4] [3]	-	895	mW
			[1] [3]	-	1565	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

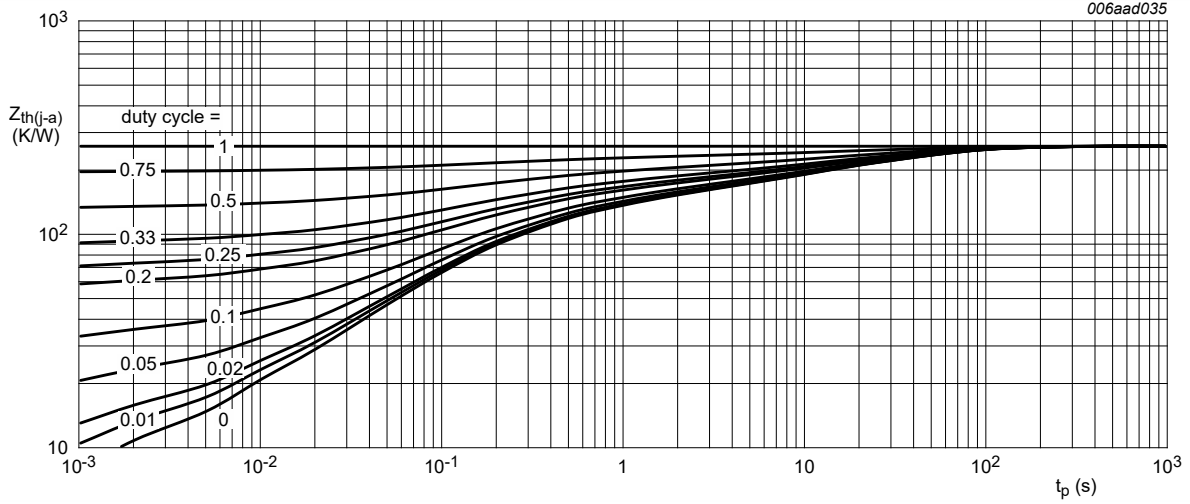
- [1] Device mounted on a ceramic Printed-Circuit Board (PCB), Al_2O_3 , standard footprint.
 [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
 [3] Reflow soldering is the only recommended soldering method.
 [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

9. Thermal characteristics

Table 6. Thermal characteristics

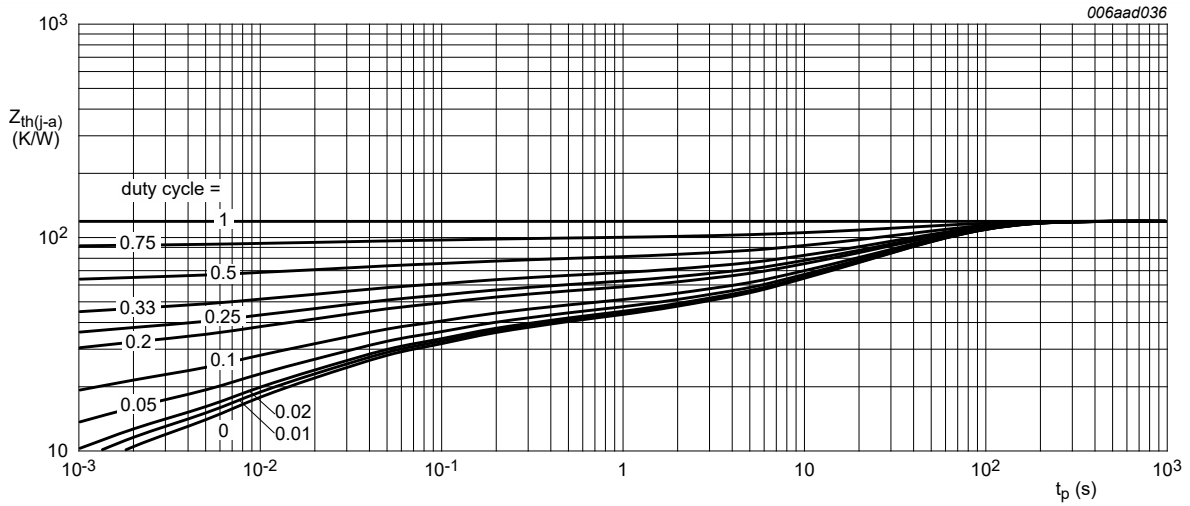
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2] [3]	-	-	300	K/W
			[1] [4] [3]	-	-	140	K/W
			[1] [5] [3]	-	-	80	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	20	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
 [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
 [3] Reflow soldering is the only recommended soldering method.
 [4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .
 [5] Device mounted on a ceramic PCB, Al_2O_3 , standard footprint.
 [6] Soldering point of cathode tab.



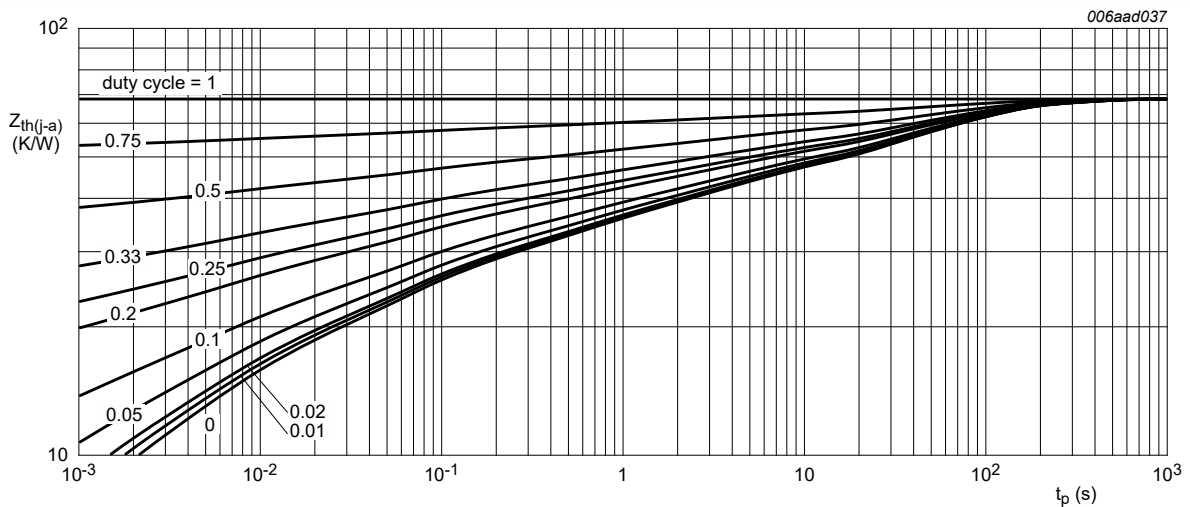
FR4 PCB, standard footprint

Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm²

Fig. 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



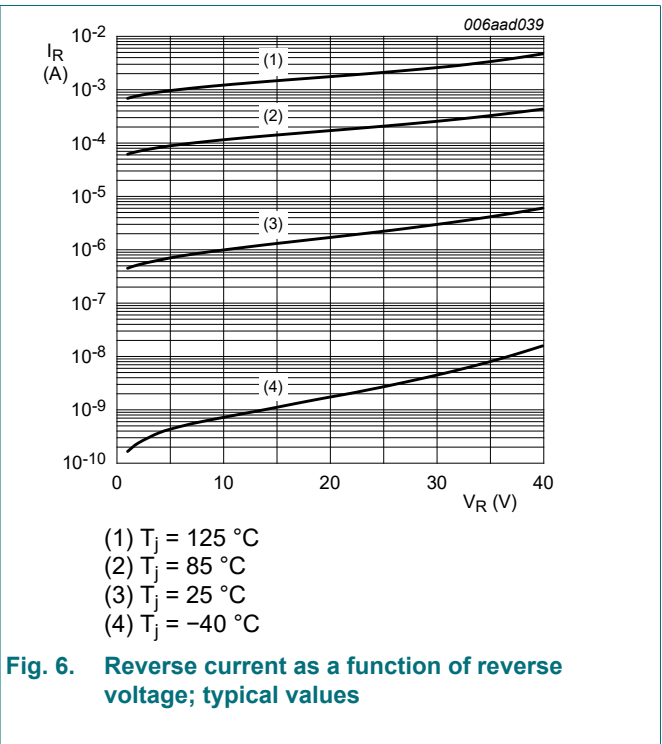
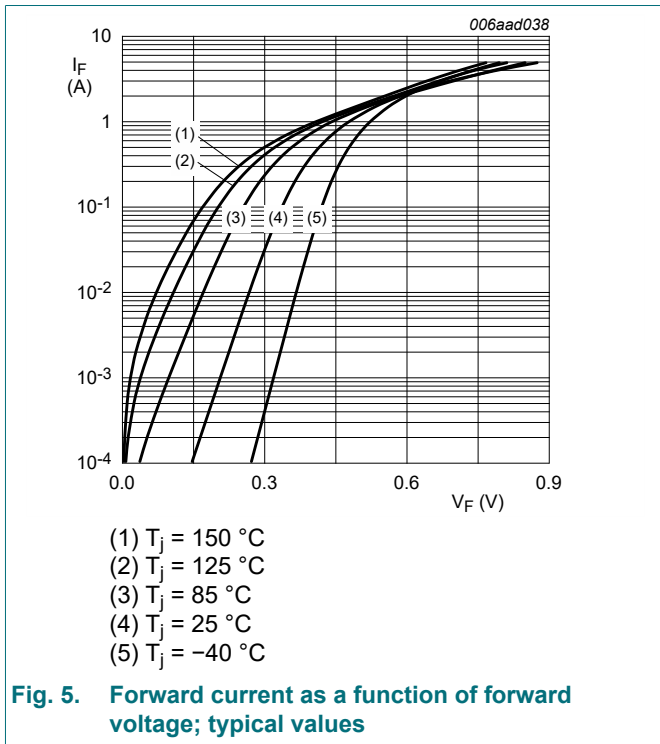
Ceramic PCB, Al₂O₃, standard footprint

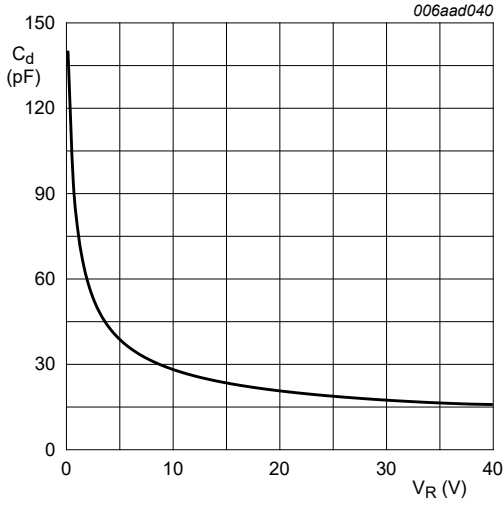
Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

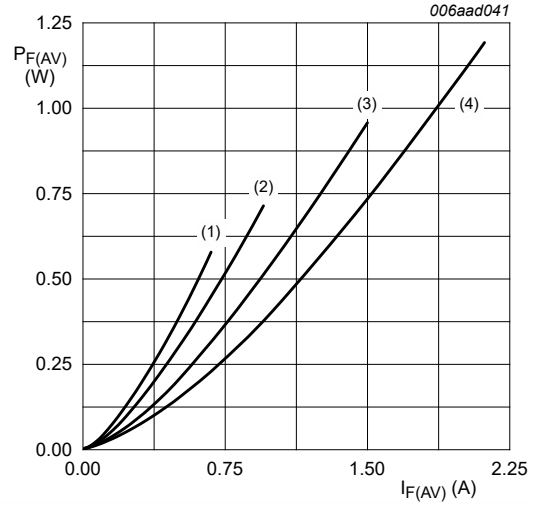
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _F	forward voltage	I _F = 100 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C	-	330	380	mV
		I _F = 500 mA; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C	-	415	480	mV
		I _F = 1 A; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C	-	490	550	mV
		I _F = 1.5 A; pulsed; t _p ≤ 300 μs; δ ≤ 0.02; T _j = 25 °C	-	540	610	mV
I _R	reverse current	V _R = 10 V; T _j = 25 °C	-	1	5	μA
		V _R = 40 V; T _j = 25 °C	-	8	30	μA
C _d	diode capacitance	V _R = 1 V; f = 1 MHz; T _j = 25 °C	-	75	90	pF
		V _R = 10 V; f = 1 MHz; T _j = 25 °C	-	30	40	pF
t _{rr}	reverse recovery time	I _F = 0.5 A; I _R = 0.5 A; I _{R(meas)} = 0.1 A; T _j = 25 °C	-	4	-	ns
V _{FRM}	peak forward recovery voltage	I _F = 0.5 A; dI _F /dt = 20 A/μs; T _j = 25 °C	-	440	-	mV





$f = 1 \text{ MHz}; T_{amb} = 25 \text{ }^\circ\text{C}$

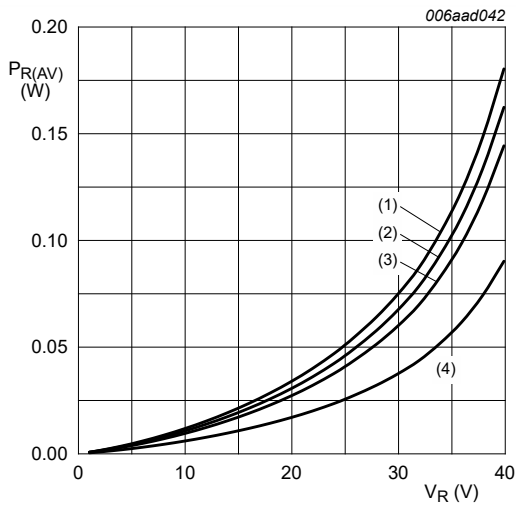
Fig. 7. Diode capacitance as a function of reverse voltage; typical values



$T_j = 150 \text{ }^\circ\text{C}$

- (1) $\delta = 0.1$
- (2) $\delta = 0.2$
- (3) $\delta = 0.5$
- (4) $\delta = 1$

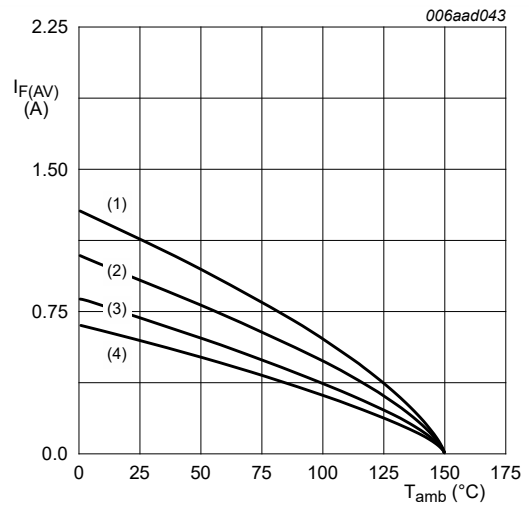
Fig. 8. Average forward power dissipation as a function of average forward current; typical values



$T_j = 125 \text{ }^\circ\text{C}$

- (1) $\delta = 1$
- (2) $\delta = 0.9$
- (3) $\delta = 0.8$
- (4) $\delta = 0.5$

Fig. 9. Average reverse power dissipation as a function of reverse voltage; typical values

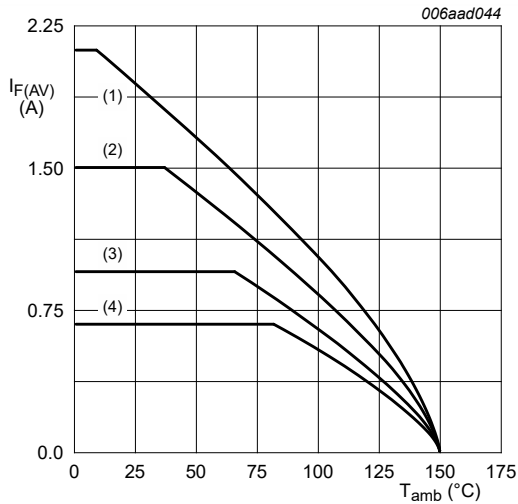


FR4 PCB, standard footprint

$T_j = 150 \text{ }^\circ\text{C}$

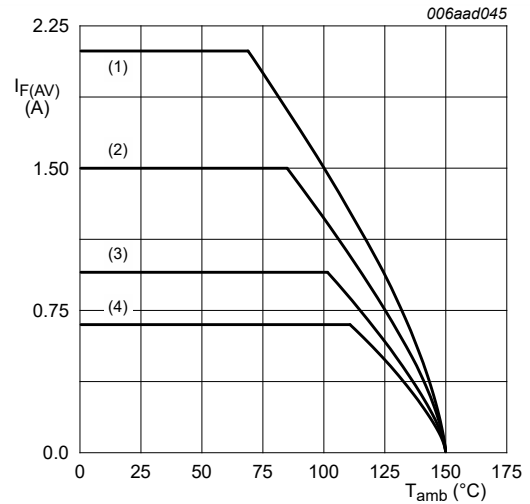
- (1) $\delta = 1$ (DC)
- (2) $\delta = 0.5; f = 20 \text{ kHz}$
- (3) $\delta = 0.2; f = 20 \text{ kHz}$
- (4) $\delta = 0.1; f = 20 \text{ kHz}$

Fig. 10. Average forward current as a function of ambient temperature; typical values



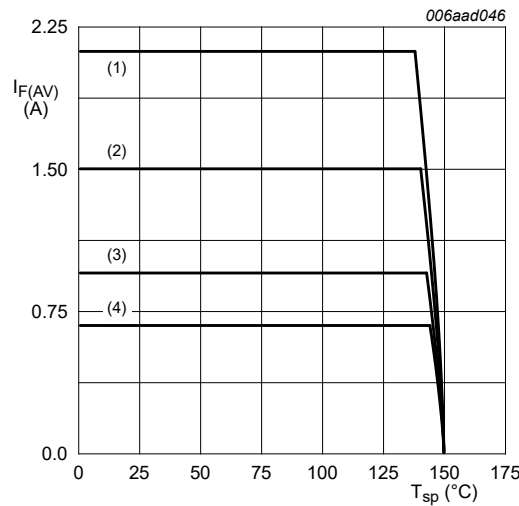
FR4 PCB, mounting pad for cathode 1 cm²
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al₂O₃, standard footprint
 $T_j = 150\text{ °C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 12. Average forward current as a function of ambient temperature; typical values



$T_j = 150\text{ °C}$
 (1) $\delta = 1$ (DC)
 (2) $\delta = 0.5$; $f = 20\text{ kHz}$
 (3) $\delta = 0.2$; $f = 20\text{ kHz}$
 (4) $\delta = 0.1$; $f = 20\text{ kHz}$

Fig. 13. Average forward current as a function of solder point temperature; typical values

11. Test information

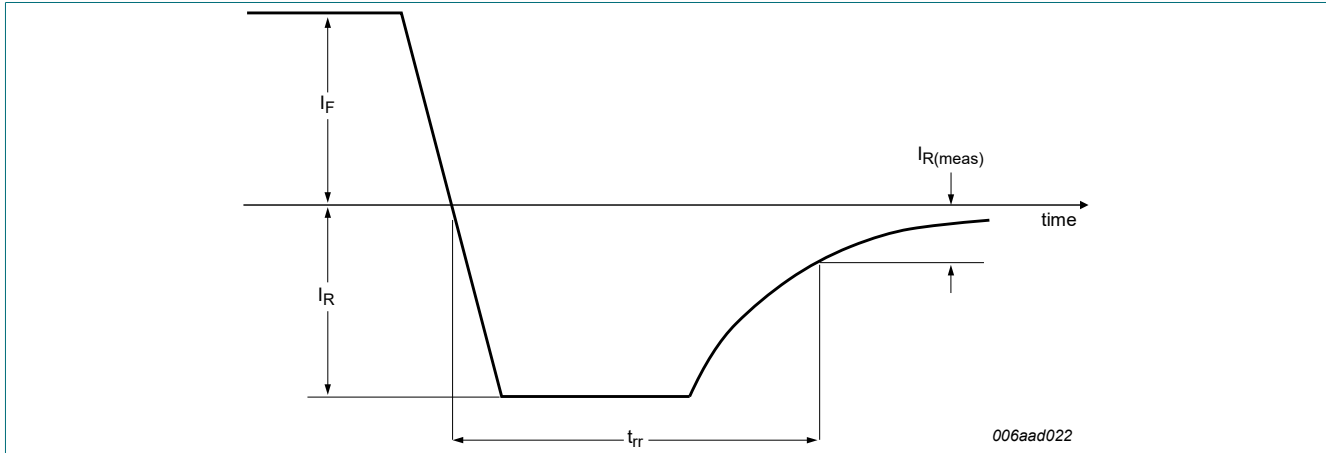


Fig. 14. Reverse recovery definition

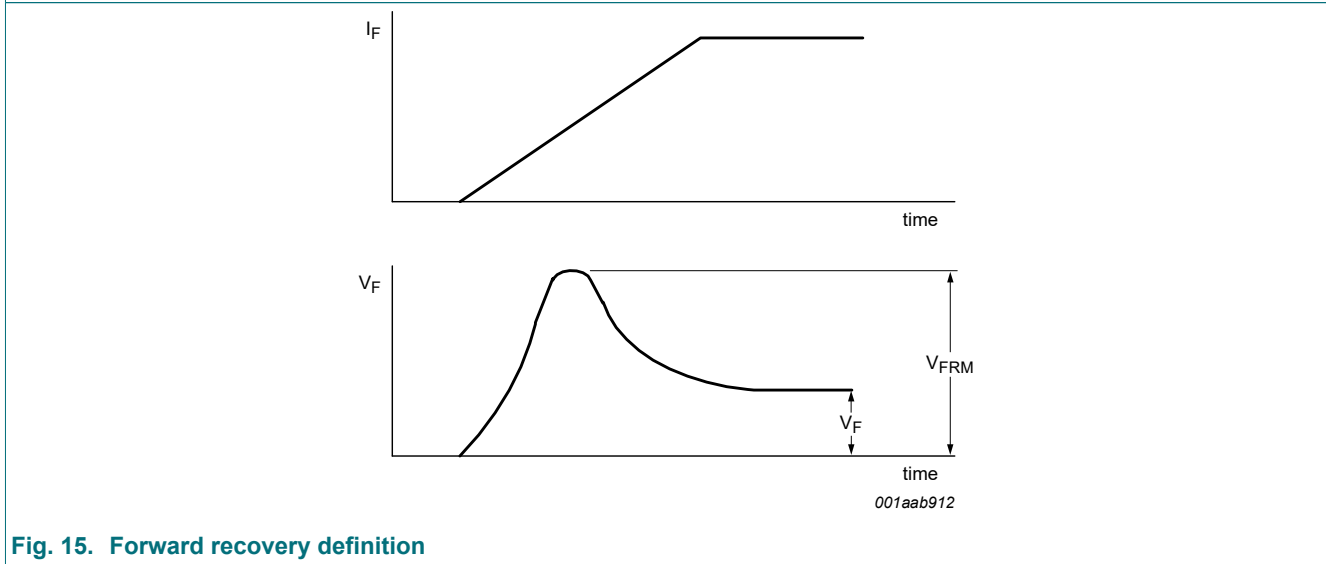


Fig. 15. Forward recovery definition

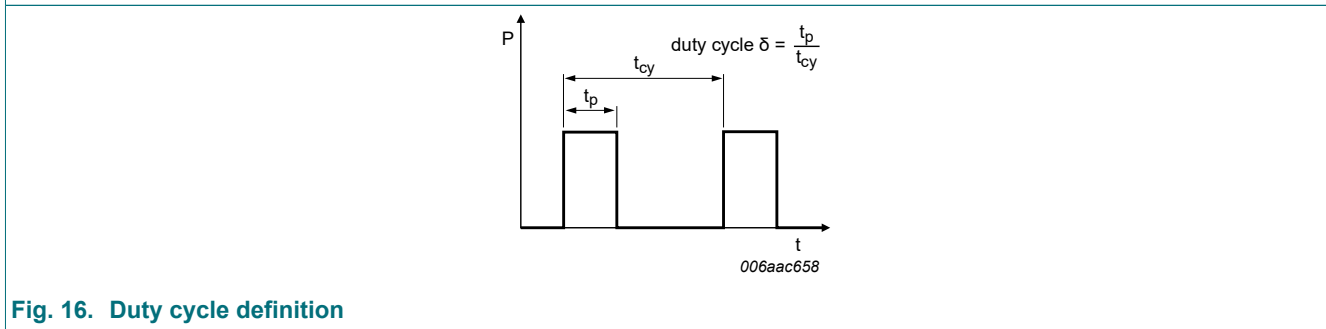


Fig. 16. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current,}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC,}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current.}$$

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

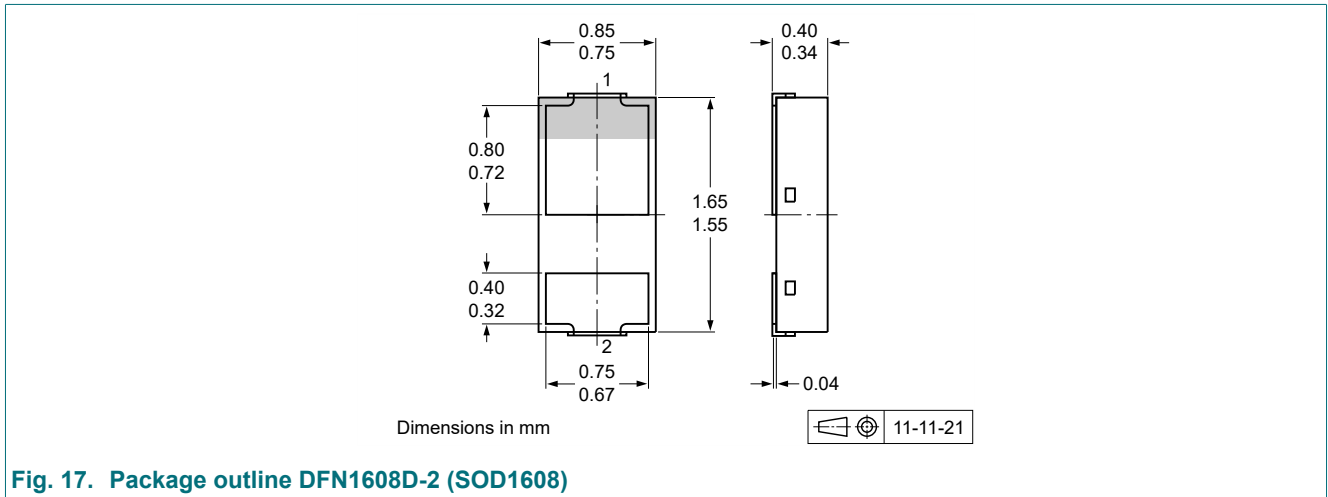


Fig. 17. Package outline DFN1608D-2 (SOD1608)

13. Soldering

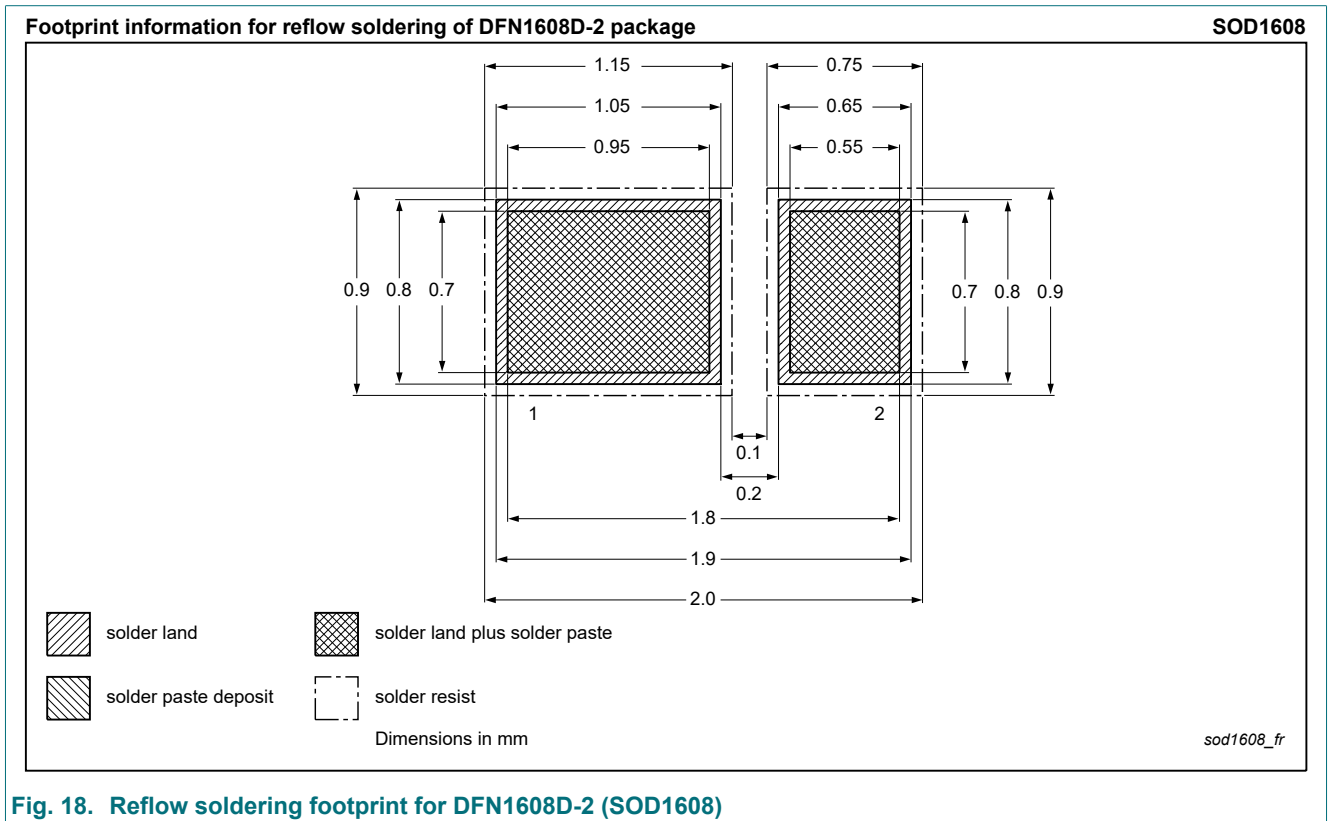


Fig. 18. Reflow soldering footprint for DFN1608D-2 (SOD1608)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG4015EPK-Q v.1	20230920	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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